



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	XCore
Core Size	32-Bit 10-Core
Speed	2000MIPS
Connectivity	-
Peripherals	-
Number of I/O	88
Program Memory Size	-
Program Memory Type	ROMIess
EEPROM Size	-
RAM Size	512K x 8
Voltage - Supply (Vcc/Vdd)	0.95V ~ 3.6V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	128-TQFP Exposed Pad
Supplier Device Package	128-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/xmos/xl210-512-tq128-c20

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Table of Contents

1	xCORF Multicore Microcontrollers	2
2	XI 210-512-TQ128 Features	4
3	Pin Configuration	5
4	Signal Description	6
5	Example Application Diagram	Õ
6	Product Overview	ĩ
7	PI1 1	4
8	Boot Procedure	5
ğ	Memory 1	8
10	TAC 1	ğ
11	Board Integration 2	0
12	DC and Switching Characteristics	2
13	Package Information 2	6
14	Ordering Information 2	7
Ann	endices 2	8
Δ	Configuration of the XI 210-512-TO128	8
R	Processor Status Configuration	0
c	Tile Configuration 4	ŭ
D D	Node Configuration 4	ġ
F	TAC vSCOPF and Debugging	7
Ē	Schematics Design Check List	à
Ċ	PCR Lavout Design Check List	; í
н	Associated Design Documentation	:2
Π.	Related Documentation	2
1	Pavision History	2
J	Newsion History	,)

TO OUR VALUED CUSTOMERS

It is our intention to provide you with accurate and comprehensive documentation for the hardware and software components used in this product. To subscribe to receive updates, visit http://www.xmos.com/.

XMOS Ltd. is the owner or licensee of the information in this document and is providing it to you "AS IS" with no warranty of any kind, express or implied and shall have no liability in relation to its use. XMOS Ltd. makes no representation that the information, or any particular implementation thereof, is or will be free from any claims of infringement and again, shall have no liability in relation to any such claims.

XMOS and the XMOS logo are registered trademarks of XMOS Ltd in the United Kingdom and other countries, and may not be used without written permission. Company and product names mentioned in this document are the trademarks or registered trademarks of their respective owners.

X007786,



In many cases I/O signals are accompanied by strobing signals. The xCORE ports can input and interpret strobe (known as readyIn and readyOut) signals generated by external sources, and ports can generate strobe signals to accompany output data.

On reset, each port is connected to clock block 0, which runs from the xCORE Tile reference clock.

6.5 Channels and Channel Ends

Logical cores communicate using point-to-point connections, formed between two channel ends. A channel-end is a resource on an xCORE tile, that is allocated by the program. Each channel-end has a unique system-wide identifier that comprises a unique number and their tile identifier. Data is transmitted to a channel-end by an output-instruction; and the other side executes an input-instruction. Data can be passed synchronously or asynchronously between the channel ends.

6.6 xCONNECT Switch and Links

XMOS devices provide a scalable architecture, where multiple xCORE devices can be connected together to form one system. Each xCORE device has an xCONNECT interconnect that provides a communication infrastructure for all tasks that run on the various xCORE tiles on the system.

The interconnect relies on a collection of switches and XMOS links. Each xCORE device has an on-chip switch that can set up circuits or route data. The switches are connected by xConnect Links. An XMOS link provides a physical connection between two switches. The switch has a routing algorithm that supports many different topologies, including lines, meshes, trees, and hypercubes.

The links operate in either 2 wires per direction or 5 wires per direction mode, depending on the amount of bandwidth required. Circuit switched, streaming and packet switched data can both be supported efficiently. Streams provide the fastest possible data rates between xCORE Tiles (up to 250 MBit/s), but each stream requires a single link to be reserved between switches on two tiles. All packet communications can be multiplexed onto a single link.



Figure 6: Switch, links and channel ends

Information on the supported routing topologies that can be used to connect multiple devices together can be found in the XS1-L Link Performance and Design Guide, X2999.

7 PLL

The PLL creates a high-speed clock that is used for the switch, tile, and reference clock. The initial PLL multiplication value is shown in Figure 7:

Figure 7: The initial PLL multiplier values

7. _L	Oscillator	Tile Boot	PLL Ratio	PLL :	settin	gs
er	Frequency	Frequency		OD	F	R
es	9-25 MHz	144-400 MHz	16	1	63	0

Figure 7 also lists the values of OD, F and R, which are the registers that define the ratio of the tile frequency to the oscillator frequency:

$$F_{core} = F_{osc} \times \frac{F+1}{2} \times \frac{1}{R+1} \times \frac{1}{OD+1}$$

OD, *F* and *R* must be chosen so that $0 \le R \le 63$, $0 \le F \le 4095$, $0 \le OD \le 7$, and $260MHz \le F_{osc} \times \frac{F+1}{2} \times \frac{1}{R+1} \le 1.3GHz$. The *OD*, *F*, and *R* values can be modified by writing to the digital node PLL configuration register.

If a different tile frequency is required (eg, 500 MHz), then the PLL must be reprogrammed after boot to provide the required tile frequency. The XMOS tools perform this operation by default. Further details on configuring the clock can be found in the xCORE-200 Clock Frequency Control document.

8 Boot Procedure

The device is kept in reset by driving RST_N low. When in reset, all GPIO pins have a pull-down enabled. When the device is taken out of reset by releasing RST_N the processor starts its internal reset process. After 15-150 μ s (depending on the input clock) the processor boots.

The xCORE Tile boot procedure is illustrated in Figure 8. If bit 5 of the security register (*see* §9.1) is set, the device boots from OTP. To get a high value, a 3K3 pull-up resistor should be strapped onto the pin. To assure a low value, a pull-down resistor is required if other external devices are connected to this port.



	X0D06	X0D05	X0D04	Tile 0 boot	Tile 1 boot	Enabled links
	0	0	0	QSPI master	Channel end 0	None
	0	0	1	SPI master	Channel end 0	None
Figure 9:	0	1	0	SPI slave	Channel end 0	None
Boot source	0	1	1	SPI slave	SPI slave	None
pins	1	0	0	Channel end 0	Channel end 0	XL0 (2w)

The boot image has the following format:

- A 32-bit program size *s* in words.
- Program consisting of $s \times 4$ bytes.
- A 32-bit CRC, or the value 0x0D15AB1E to indicate that no CRC check should be performed.

The program size and CRC are stored least significant byte first. The program is loaded into the lowest memory address of RAM, and the program is started from that address. The CRC is calculated over the byte stream represented by the program size and the program itself. The polynomial used is 0xEDB88320 (IEEE

8.3 Boot from SPI slave

If set to boot from SPI slave, the processor enables the three pins specified in Figure 12 and expects a boot image to be clocked in. The supported clock polarity and phase are 0/0 and 1/1.

	Pin	Signal	Description
	X0D00	SS	Slave Select
Figure 12:	X0D10	SCLK	Clock
SPI slave pins	X0D11	MOSI	Master Out Slave In (Data)

The xCORE Tile expects each byte to be transferred with the *least-significant bit first*. The pins used for SPI boot are hardcoded in the boot ROM and cannot be changed. If required, an SPI boot program can be burned into OTP that uses different pins.

8.4 Boot from xConnect Link

If set to boot from an xConnect Link, the processor enables its link(s) around 2 us after the boot process starts. Enabling the Link switches off the pull-down resistors on the link, drives all the TX wires low (the initial state for the Link), and monitors the RX pins for boot-traffic; they must be low at this stage. If the internal pull-down is too weak to drain any residual charge, external pull-downs of 10K may be required on those pins.

The boot-rom on the core will then:

- 1. Allocate channel-end 0.
- 2. Input a word on channel-end 0. It will use this word as a channel to acknowledge the boot. Provide the null-channel-end 0x0000FF02 if no acknowledgment is required.
- 3. Input the boot image specified above, including the CRC.
- 4. Input an END control token.
- 5. Output an END control token to the channel-end received in step 2.
- 6. Free channel-end 0.
- 7. Jump to the loaded code.

8.5 Boot from OTP

If an xCORE tile is set to use secure boot (see Figure 8), the boot image is read from address 0 of the OTP memory in the tile's security module.

This feature can be used to implement a secure bootloader which loads an encrypted image from external flash, decrypts and CRC checks it with the processor, and discontinues the boot process if the decryption or CRC check fails. XMOS



12.3 ESD Stress Voltage

Figure 20 ESD stress voltage

20:	Symbol	Parameter	MIN	ТҮР	MAX	UNITS	Notes
255	HBM	Human body model	-2.00		2.00	KV	
lge	CDM	Charged Device Model	-500		500	V	

12.4 Reset Timing

	Symbol	Parameters	MIN	TYP	MAX	UNITS	Notes	
Figure 21:	T(RST)	Reset pulse width	5			μs		
Reset timing	T(INIT)	Initialization time			150	μs	А	
	A Channe the time taken to start be sting after DCT N has none high							

A Shows the time taken to start booting after RST_N has gone high.

12.5 Power Consumption

	Symbol	Parameter	MIN	ТҮР	MAX	UNITS	Notes
	I(DDCQ)	Quiescent VDD current		45		mA	A, B, C
Figure 22:	PD	Tile power dissipation		325		µW/MIPS	A, D, E, F
xCORE Tile currents	IDD	Active VDD current		570	700	mA	A, G
	I(ADDPLL)	PLL_AVDD current		5	7	mA	Н

A Use for budgetary purposes only.

B Assumes typical tile and I/O voltages with no switching activity.

- C Includes PLL current.
- D Assumes typical tile and I/O voltages with nominal switching activity.
- E Assumes 1 MHz = 1 MIPS.
- F PD(TYP) value is the usage power consumption under typical operating conditions.
- G Measurement conditions: VDD = 1.0 V, VDDIO = 3.3 V, 25 °C, 500 MHz, average device resource usage.
- H PLL_AVDD = 1.0 V



The tile power consumption of the device is highly application dependent and should be used for budgetary purposes only.



The asynchronous nature of links means that the relative phasing of CLK clocks is not important in a multi-clock system, providing each meets the required stability criteria.

Symbol	Parameter	MIN	ТҮР	MAX	UNITS	Notes
f(TCK_D)	TCK frequency (debug)			18	MHz	
f(TCK_B)	TCK frequency (boundary scan)			10	MHz	
T(SETUP)	TDO to TCK setup time	5			ns	А
T(HOLD)	TDO to TCK hold time	5			ns	А
T(DELAY)	TCK to output delay			15	ns	В

12.9 JTAG Timing

Figure 26: JTAG timing

A Timing applies to TMS and TDI inputs.

B Timing applies to TDO output from negative edge of TCK.

All JTAG operations are synchronous to TCK apart from the global asynchronous reset TRST_N.



Bits	Perm	Init	Description
31:11	RO	-	Reserved
10	DRW		Address space indentifier
9	DRW		Determines the issue mode (DI bit) upon Kernel Entry after Exception or Interrupt.
8	RO		Determines the issue mode (DI bit).
7	DRW		When 1 the thread is in fast mode and will continually issue.
6	DRW		When 1 the thread is paused waiting for events, a lock or another resource.
5	RO	-	Reserved
4	DRW		1 when in kernel mode.
3	DRW		1 when in an interrupt handler.
2	DRW		1 when in an event enabling sequence.
1	DRW		When 1 interrupts are enabled for the thread.
0	DRW		When 1 events are enabled for the thread.

0x10: Debug SSR

B.13 Debug SPC: 0x11

This register contains the value of the SPC register when the debugger was called.

0x11:	Bits	Perm	Init	Description
Debug SPC	31:0	DRW		Value.

B.14 Debug SSP: 0x12

This register contains the value of the SSP register when the debugger was called.

0x12:	Bits	Perm	Init	Description
Debug SSP	31:0	DRW		Value.

B.15 DGETREG operand 1: 0x13

The resource ID of the logical core whose state is to be read.

-XMOS

0x13:	Bits	Perm	Init	Description
DGETREG	31:8	RO	-	Reserved
operand 1	7:0	DRW		Thread number to be read

B.16 DGETREG operand 2: 0x14

Register number to be read by DGETREG

0x14: DGETREG operand 2

Bits	Perm	Init	Description
31:5	RO	-	Reserved
4:0	DRW		Register number to be read

B.17 Debug interrupt type: 0x15

Register that specifies what activated the debug interrupt.

Bits	Perm	Init	Description
31:18	RO	-	Reserved
17:16	DRW		Number of the hardware breakpoint/watchpoint which caused the interrupt (always 0 for =HOST= and =DCALL=). If multiple breakpoints/watchpoints trigger at once, the lowest number is taken.
15:8	DRW		Number of thread which caused the debug interrupt (always 0 in the case of =HOST=).
7:3	RO	-	Reserved
2:0	DRW	0	Indicates the cause of the debug interrupt 1: Host initiated a debug interrupt through JTAG 2: Program executed a DCALL instruction 3: Instruction breakpoint 4: Data watch point 5: Resource watch point

0x15: Debug interrupt type

B.18 Debug interrupt data: 0x16

On a data watchpoint, this register contains the effective address of the memory operation that triggered the debugger. On a resource watchpoint, it countains the resource identifier.

-XMOS-

Ox16:
Debug
interrupt dataBitsPermInitDescription31:0DRWValue.

B.19 Debug core control: 0x18

This register enables the debugger to temporarily disable logical cores. When returning from the debug interrupts, the cores set in this register will not execute. This enables single stepping to be implemented.

0x18: Debug core control

Bits	Perm	Init	Description
31:8	RO	-	Reserved
7:0	DRW		1-hot vector defining which threads are stopped when not in debug mode. Every bit which is set prevents the respective thread from running.

B.20 Debug scratch: 0x20 .. 0x27

A set of registers used by the debug ROM to communicate with an external debugger, for example over JTAG. This is the same set of registers as the Debug Scratch registers in the xCORE tile configuration.

0x20 .. 0x27: Debug scratch

cz7: bug	Bits	Perm	Init	Description
ıtch	31:0	DRW		Value.

B.21 Instruction breakpoint address: 0x30 .. 0x33

This register contains the address of the instruction breakpoint. If the PC matches this address, then a debug interrupt will be taken. There are four instruction breakpoints that are controlled individually.

0x30 .. 0x33: Instruction breakpoint address

tion bint	Bits	Perm	Init	Description
ess	31:0	DRW		Value.

	Bits	Perm	Init	Description
	31:24	RO	-	Reserved
	23:16	DRW	0	A bit for each thread in the machine allowing the breakpoint to be enabled individually for each thread.
0x70 0x73:	15:3	RO	-	Reserved
Data break point	2	DRW	0	When 1 the breakpoints will be be triggered on loads.
control	1	DRW	0	Determines the break condition: $0 = A AND B$, $1 = A OR B$.
register	0	DRW	0	When 1 the instruction breakpoint is enabled.

B.26 Resources breakpoint mask: 0x80 .. 0x83

This set of registers contains the mask for the four resource watchpoints.

0x80 0x83:				
breakpoint	Bits	Perm	Init	Description
mask	31:0	DRW		Value.

B.27 Resources breakpoint value: 0x90 .. 0x93

This set of registers contains the value for the four resource watchpoints.

0x90 0x93:				
breakpoint	Bits	Perm	Init	Description
value	31:0	DRW		Value.

B.28 Resources breakpoint control register: 0x9C .. 0x9F

This set of registers controls each of the four resource watchpoints.

-XMOS

39

	Bits	Perm	Init	Description
	31:24	RO	-	Reserved
	23:16	DRW	0	A bit for each thread in the machine allowing the breakpoint to be enabled individually for each thread.
0x9C 0x9F:	15:2	RO	-	Reserved
breakpoint control	1	DRW	0	When 0 break when condition A is met. When 1 = break when condition B is met.
register	0	DRW	0	When 1 the instruction breakpoint is enabled.

40



C Tile Configuration

The xCORE Tile control registers can be accessed using configuration reads and writes (use write_tile_config_reg(tileref, ...) and read_tile_config_reg(tileref, \rightarrow ...) for reads and writes).

Number	Perm	Description
0x00	CRO	Device identification
0x01	CRO	xCORE Tile description 1
0x02	CRO	xCORE Tile description 2
0x04	CRW	Control PSwitch permissions to debug registers
0x05	CRW	Cause debug interrupts
0x06	CRW	xCORE Tile clock divider
0x07	CRO	Security configuration
0x20 0x27	CRW	Debug scratch
0x40	CRO	PC of logical core 0
0x41	CRO	PC of logical core 1
0x42	CRO	PC of logical core 2
0x43	CRO	PC of logical core 3
0x44	CRO	PC of logical core 4
0x45	CRO	PC of logical core 5
0x46	CRO	PC of logical core 6
0x47	CRO	PC of logical core 7
0x60	CRO	SR of logical core 0
0x61	CRO	SR of logical core 1
0x62	CRO	SR of logical core 2
0x63	CRO	SR of logical core 3
0x64	CRO	SR of logical core 4
0x65	CRO	SR of logical core 5
0x66	CRO	SR of logical core 6
0x67	CRO	SR of logical core 7

Figure 31: Summary

C.1 Device identification: 0x00

This register identifies the xCORE Tile

-XMOS°

	Bits	Perm	Init	Description
	31	CRO		Disables write permission on this register
	30:15	RO	-	Reserved
	14	CRO		Disable access to XCore's global debug
	13	RO	-	Reserved
	12	CRO		lock all OTP sectors
	11:8	CRO		lock bit for each OTP sector
	7	CRO		Enable OTP reduanacy
	6	RO	-	Reserved
	5	CRO		Override boot mode and read boot image from OTP
	4	CRO		Disable JTAG access to the PLL/BOOT configuration registers
,	3:1	RO	-	Reserved
-	0	CRO		Disable access to XCore's JTAG debug TAP

0x07 Security configuration

C.8 Debug scratch: 0x20 .. 0x27

A set of registers used by the debug ROM to communicate with an external debugger, for example over the switch. This is the same set of registers as the Debug Scratch registers in the processor status.

0x20 .. 0x27: Debug scratch

ebug	Bits	Perm	Init	Description
ratch	31:0	CRW		Value.

C.9 PC of logical core 0: 0x40

Value of the PC of logical core 0.

0x40 PC of logical core 0

ical re 0	Bits	Perm	Init	Description
	31:0	CRO		Value.

-XMOS

C.10 PC of logical core 1: 0x41

Value of the PC of logical core 1.



C.24 SR of logical core 7: 0x67

Value of the SR of logical core 7

0x67				
SR of logical core 7	Bits	Perm	Init	Description
	31:0	CRO		Value.



D.8 System JTAG device ID register: 0x09

0x09: System JTAG device ID register

	Bits	Perm	Init	Description
•	31:28	RO		
	27:12	RO		
)	11:1	RO		
	0	RO		

D.9 System USERCODE register: 0x0A

0x0A System USERCODE register

:	Bits	Perm	Init	Description
Ē	31:18	RO		JTAG USERCODE value programmed into OTP SR
r	17:0	RO		metal fixable ID code

D.10 Directions 0-7: 0x0C

This register contains eight directions, for packets with a mismatch in bits 7..0 of the node-identifier. The direction in which a packet will be routed is goverened by the most significant mismatching bit.

Bits	Perm	Init	Description	
31:28	RW	0	The direction for packets whose dimension is 7.	
27:24	RW	0	The direction for packets whose dimension is 6.	
23:20	RW	0	The direction for packets whose dimension is 5.	
19:16	RW	0	The direction for packets whose dimension is 4.	
15:12	RW	0	The direction for packets whose dimension is 3.	
11:8	RW	0	The direction for packets whose dimension is 2.	
7:4	RW	0	The direction for packets whose dimension is 1.	
3:0	RW	0	The direction for packets whose dimension is 0.	

0x0C: Directions 0-7

D.11 Directions 8-15: 0x0D

This register contains eight directions, for packets with a mismatch in bits 15..8 of the node-identifier. The direction in which a packet will be routed is goverened by the most significant mismatching bit.

-XMOS-

Bits	Perm	Init	Description
31:5	RO	-	Reserved
4	RW		Reserved.
3:2	RO	-	Reserved
1	RW		If set, XCore1 is the source of last GlobalDebug event.
0	RW		If set, XCore0 is the source of last GlobalDebug event.

0x1F: Debug source

D.15 Link status, direction, and network: 0x20 .. 0x28

These registers contain status information for low level debugging (read-only), the network number that each link belongs to, and the direction that each link is part of. The registers control links 0..7.

Bits	Perm	Init	Description	
31:26	RO	-	Reserved	
25:24	RO		Identify the SRC_TARGET type 0 - SLink, 1 - PLink, 2 - SSCTL, 3 - Undefine.	
23:16	RO		When the link is in use, this is the destination link number to which all packets are sent.	
15:12	RO	-	Reserved	
11:8	RW	0	The direction that this link operates in.	
7:6	RO	-	Reserved	
5:4	RW	0	Determines the network to which this link belongs, reset as 0.	
3	RO	-	Reserved	
2	RO		1 when the current packet is considered junk and will be thrown away.	
1	RO		1 when the dest side of the link is in use.	
0	RO		1 when the source side of the link is in use.	

0x20 .. 0x28: Link status, direction, and network

D.16 PLink status and network: 0x40 .. 0x47

These registers contain status information and the network number that each processor-link belongs to.

-XMOS-

D.18 Static link configuration: 0xA0 .. 0xA7

These registers are used for static (ie, non-routed) links. When a link is made static, all traffic is forwarded to the designated channel end and no routing is attempted. The registers control links C, D, A, B, G, H, E, and F in that order.

Bits	Perm	Init	Description
31	RW	0	Enable static forwarding.
30:9	RO	-	Reserved
8	RW	0	The destination processor on this node that packets received in static mode are forwarded to.
7:5	RO	-	Reserved
4:0	RW	0	The destination channel end on this node that packets received in static mode are forwarded to.

0xA0 .. 0xA7: Static link configuration





E JTAG, xSCOPE and Debugging

If you intend to design a board that can be used with the XMOS toolchain and xTAG debugger, you will need an xSYS header on your board. Figure 33 shows a decision diagram which explains what type of xSYS connectivity you need. The three subsections below explain the options in detail.



E.1 No xSYS header

The use of an xSYS header is optional, and may not be required for volume production designs. However, the XMOS toolchain expects the xSYS header; if you do not have an xSYS header then you must provide your own method for writing to flash/OTP and for debugging.

E.2 JTAG-only xSYS header

The xSYS header connects to an xTAG debugger, which has a 20-pin 0.1" female IDC header. The design will hence need a male IDC header. We advise to use a boxed header to guard against incorrect plug-ins. If you use a 90 degree angled header, make sure that pins 2, 4, 6, ..., 20 are along the edge of the PCB.

Connect pins 4, 8, 12, 16, 20 of the xSYS header to ground, and then connect:

 \mathbf{X} M()S

- ▶ TDI to pin 5 of the xSYS header
- TMS to pin 7 of the xSYS header
- TCK to pin 9 of the xSYS header
- TDO to pin 13 of the xSYS header

H Associated Design Documentation

Document Title	Information	Document Number
Estimating Power Consumption For XS1-L Devices	Power consumption	X4271
Programming XC on XMOS Devices	Timers, ports, clocks, cores and channels	X9577
xTIMEcomposer User Guide	Compilers, assembler and linker/mapper	X3766
	Timing analyzer, xScope, debugger	
	Flash and OTP programming utilities	

I Related Documentation

Document Title	Information	Document Number
The XMOS XS1 Architecture	ISA manual	X7879
XS1 Port I/O Timing	Port timings	X5821
xCONNECT Architecture	Link, switch and system information	X4249
XS1-L Link Performance and Design Guidelines	Link timings	X2999
XS1-L Clock Frequency Control	Advanced clock control	X1433
XS1-L Active Power Conservation	Low-power mode during idle	X7411

-XMOS[®]-

62